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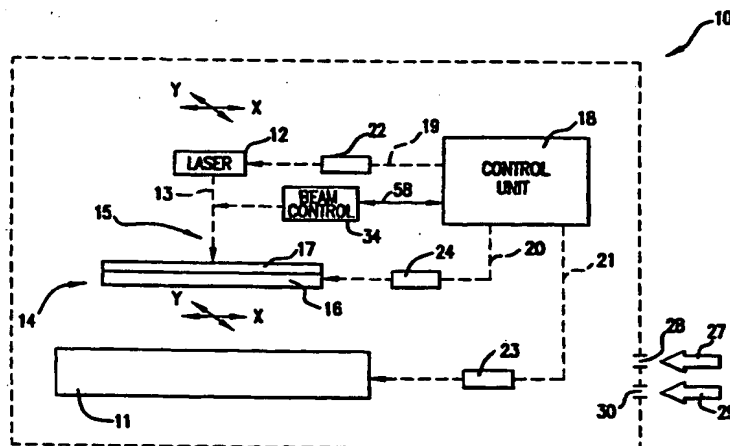
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(54) Title: PATTERNED SURFACE CLEANING SYSTEM OF MINIATURE STRUCTURES



(57) Abstract: Apparatus (10) for performing patterned cleaning of substrate surfaces (11) includes substrate (11), energetic beam (12) directed to the substrate (11), material carrier element (14) having a deposition layer (16), and a control unit (8) operating the apparatus (10) in either a "material removal" or a "material transfer" mode in a predetermined sequence. In the "material removal" mode, the following steps are followed which include displacing the material carrier element (14) from the interception with the energy beam (12) and allowing impinging of the energy beam (12) on the surface of the substrate in a predetermined patterned fashion so that the material of the substrate surface is disintegrated at predetermined locations of the substrate surface (11). After the first cleaning, the control unit (18) changes the mode of operation to the "material transfer" by moving the material carrier element (14) into position intercepting with the energy beam (12) so that the material of the deposition layer (16) is deposited on the surface of the substrate (11).